

Oki, Network Solutions for a Global Society

FEDR27V3202F-02-02

Issue Date: Mar. 12, 2002

OKI Semiconductor

MR27V3202F

2M-Word \times 16-Bit or 4M-Word \times 8-Bit P2ROM

FEATURES

- \cdot 2,097,152-word \times 16-bit/4,194,304-word \times 8-bit electrically switchable configuration
- $\cdot +3.0 \text{ V}$ to 3.6 V power supply
- Access time
 Operating current
 Standby current
 MAX
 30 mA MAX
 10 μA MAX
- · Input/Output TTL compatible
- · Three-state output

PACKAGES

- · MR27V3202F-xxMA 44-pin plastic SOP (SOP44-P-600-1.27-K)
- · MR27V3202F-xxTP

44-pin plastic TSOP (TSOP(2)44-P-400-0.80-K)

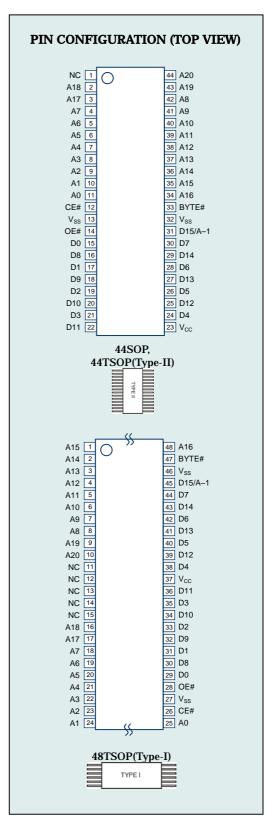
· MR27V3202F-xxTN

48-pin plastic TSOP (TSOP(1)48-P-1220-0.50-K)

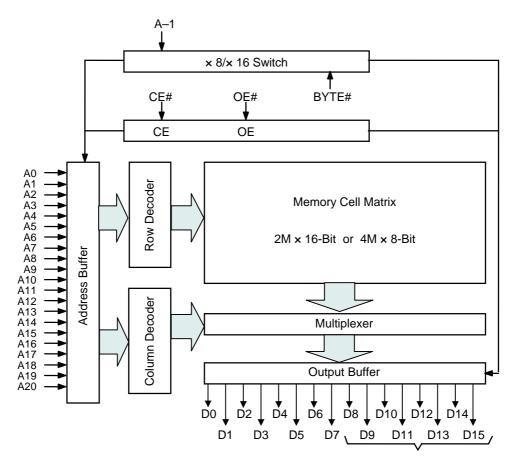
P2ROM ADVANCED TECHNOLOGY

P2ROM stands for Production Programmed ROM. This exclusive Oki technology utilizes factory test equipment for programming the customers code into the P2ROM prior to final production testing. Advancements in this technology allows production costs to be equivalent to MASKROM and has many advantages and added benefits over the other non-volatile technologies, which include the following;

- Short lead time, since the P2ROM is programmed at the final stage of the production process, a large P2ROM inventory "bank system" of un-programmed packaged products are maintained to provide an aggressive lead-time and minimize liability as a custom product.
- No mask charge, since P2ROMs do not utilize a custom mask for storing customer code, no mask charges apply.
- No additional programming charge, unlike Flash and OTP that require additional programming and handling costs, the P2ROM already has the code loaded at the factory with minimal effect on the production throughput. The cost is included in the unit price.
- Custom Marking is available at no additional charge.
- Pin Compatible with Mask ROM and some FLASH products.



BLOCK DIAGRAM



In 8-bit output mode, these pins are placed in a high-Z state and pin D15 functions as the A-1 address pin.

PIN DESCRIPTIONS

Pin name	Functions		
D15 / A-1	Data output / Address input		
A0 to A20	Address inputs		
D0 to D14	Data outputs		
CE#	Chip enable input		
OE#	Output enable input		
BYTE#	Word / Byte select input		
V _{CC}	Power supply voltage		
V _{SS}	Ground		
NC	No connect		

FUNCTION TABLE

Mode	CE#	OE#	BYTE#	V _{CC}	D0 to D7	D8 to D14	D15/A-1
Read (16-Bit)	L	L	Н			D_OUT	
Read (8-Bit)	L	L	L		D _{OUT}	Hi–Z	L/H
Output disable	L	Н	Н	3.3 V			
			L			*	
Standby	н		Н		Hi–Z		
		*	L				*

^{*:} Don't Care (H or L)

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Condition	Value	Unit
Operating temperature under bias	Та		0 to 70	°C
Storage temperature	Tstg	_	-55 to 125	°C
Input voltage	V_{I}		-0.5 to V _{CC} +0.5	V
Output voltage	Vo	relative to V _{SS}	-0.5 to V _{CC} +0.5	V
Power supply voltage	V _{CC}		–0.5 to 5	V
Power dissipation per package	P_D	_	1.0	W

RECOMMENDED OPERATING CONDITIONS

 $(Ta = 0 \text{ to } 70^{\circ}C)$

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
V _{CC} power supply voltage	V _{CC}		3.0	_	3.6	V
Input "H" level	V _{IH}	$V_{CC} = 3.0 \text{ to } 3.6 \text{ V}$	2.2	1	V _{CC} +0.5*	V
Input "L" level	V _{IL}		-0.5**	_	0.6	V

Voltage is relative to V_{SS} .

*: Vcc+1.5V(Max.) when pulse width of overshoot is less than 10ns.

PIN CAPACITANCE

 $(V_{CC} = 3.3 \text{ V}, Ta = 25^{\circ}\text{C}, f = 1 \text{ MHz})$

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Input	C _{IN1}	V ₁ = 0 V	_	_	8	
BYTE#	C _{IN2}	$V_1 = U V$	_	_	120	pF
Output	Соит	$V_O = 0 V$	_	_	10	

^{**: -1.5}V(Min.) when pulse width of undershoot is less than 10ns.

ELECTRICAL CHARACTERISTICS

DC Characteristics

 $(V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}, \text{Ta} = 0 \text{ to } 70^{\circ}\text{C})$

				\	100 0.0 1	,	/
Parameter	Symbol	Condition		Min.	Тур.	Max.	Unit
Input leakage current	ILI	$V_I = 0$ to V_{CC}		_	_	10	μΑ
Output leakage current	I _{LO}	$V_O = 0$ to V_{CC}		_	_	10	μΑ
V _{CC} power supply current	I _{ccsc}	CE# = V _{CC}		_	_	10	μΑ
(Standby)	I _{CCST}	CE# = V _{IH}		_	_	1	mA
V _{CC} power supply current	I _{CCA1}	CE# = V _{IL}	tc = 100 ns	_	_	30	mA
(Read)	I _{CCA2}	OE# = V _{IH} tc = 200 ns		_	_	20	mA
Input "H" level	V _{IH}	_		2.2	_	V _{CC} +0.5*	V
Input "L" level	V_{IL}	_		-0.5**	_	0.6	V
Output "H" level	V _{OH}	$I_{OH} = -2 \text{ mA}$		2.4	_	_	V
Output "L" level	V _{OL}	I _{OL} = 4 mA		_	_	0.4	V

Voltage is relative to V_{SS} .

- * : Vcc+1.5V(Max.) when pulse width of overshoot is less than 10ns.
- **: -1.5V(Min.) when pulse width of undershoot is less than 10ns.

AC Characteristics

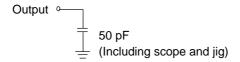
 $(V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}, \text{Ta} = 0 \text{ to } 70^{\circ}\text{C})$

Parameter	Symbol	Condition	Min.	Max.	Unit
Address cycle time	t _C	_	80	_	ns
Address access time	t _{ACC}	CE# = OE# = V _{IL}	_	80	ns
CE# access time	t _{CE}	OE# = V _{IL}	_	80	ns
OE# access time	t _{OE}	CE #= V _{IL}	_	30	ns
Output disable time	t _{CHZ}	OE# = V _{IL}	0	30	ns
Output disable time	t _{OHZ}	CE# = V _{IL}	0	25	ns
Output hold time	t _{OH}	CE #= OE# = V _{IL}	0	_	ns

Measurement conditions

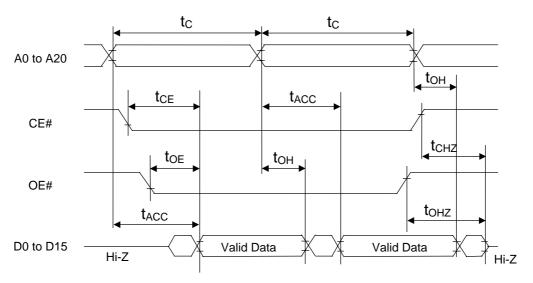
Input signal level------0 V / 3 V Input timing reference level ------1/2 Vcc Output load------50 pF Output timing reference level ------1/2 Vcc

Output load

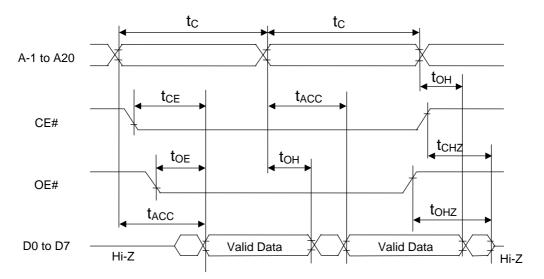


TIMING CHART (READ CYCLE)

16-Bit Read Mode (BYTE# = V_{IH})

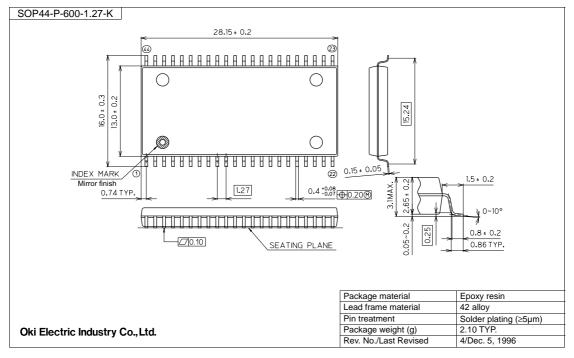


8-Bit Read Mode (BYTE# = V_{IL})



PACKAGE DIMENSIONS

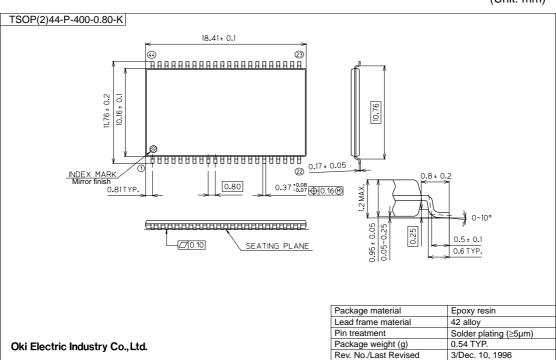
(Unit: mm)



Notes for Mounting the Surface Mount Type Package

The surface mount type packages are very susceptible to heat in reflow mounting and humidity absorbed in storage.

Therefore, before you perform reflow mounting, contact Oki's responsible sales person for the product name, package name, pin number, package code and desired mounting conditions (reflow method, temperature and times).

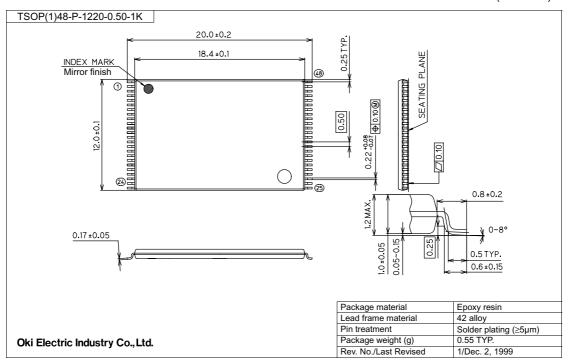


(Unit: mm)

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REVISION HISTORY

Document		Pa	ge	
No.	Date	Previous Edition	Current Edition	Description
FEDR27V3202F-02-01	Oct, 2000	-	I	Final edition 1
FEDR27V3202F-02-02	Mar. 12, 2002	5	4	Changed t _C , t _{ACC} , t _{CE} to 80ns Added I _{CCA2} at t _C = 200ns Change the symbol, I _{CCA} to I _{CCA1} Changed I _{CCA1} to 30mA Changed t _{OE} to 30ns Changed I _{CCSC} to 10uA
		1-4, 7	1-3	Changed the form

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